Yes ___ No

on back of

this page)

(Number)

DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

(Insert Title) SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME AND METHOD OF FORMING NITRIDE BASED SEMICONDUCTOR LAYER

the specification of which is attached hereto unless the following is checked:

	was filed onApplication Number_ (if applicable).		nited States Application Number or PCT International and was amended on			
I hereby sta	te that I have reviewed claim(s), as amended by	d and understand y any amendment	the contents of the above-referred to above.	identified specification,		
I acknowledge Code of Federal	ge the duty to disclose in eral Regulations, § 1.56.	nformation which	is material to the patentability	y as defined in Title 37,		
application(s) for patent or inventor or patent or inventor's c	's certificate listed	, United States Code, § 119 below and have also idential filing date before that of the	fied below any foreign		
,				Priority Claimed		
(List prior	10-213970	Japan	29/7/1998	_X_ Yes No		
foreign	(Number)	(Country)	(Day/Month/Year Filed)			
applications.				Yes No		
See note A	(Number)	(Country)	(Day/Month/Year Filed)			

(See note B on back of this page) See attached list for additional prior foreign applications

(Country)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

(Day/Month/Year Filed)

(Application Number)	(Filing Date)	
(Application Number)	(Filing Date)	

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application

(List Prior U.S. Applications)

(Appln. Serial No.) (Filing Date) (Status) (patented, pending, abandoned)

(Appln. Serial No.) (Filing Date) (Status) (patented, pending, abandoned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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Please direct all communications to the following address:

and the national or PCT international filing date of the application:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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